

# CONNECTION METHOD, CIRCUIT BOARD USING THE SAME AND ITS PRODUCING METHOD, SEMICONDUCTOR PACKAGE AND ITS MANUFACTURING METHOD

**Publication number:** JP2002185097 (A)

**Publication date:** 2002-06-28

**Inventor(s):** NAKAMURA HIDEHIRO; ENDO TOSHIHIRO; ENOMOTO TETSUYA; INOUE FUMIO; TSUBOMATSU YOSHIAKI; NAKASO AKISHI

**Applicant(s):** HITACHI CHEMICAL CO LTD

**Classification:**

- international: *C08K3/00; C08L101/00; H01L23/12; H05K1/11; H05K3/00; H05K3/42; C08K3/00; C08L101/00; C08K3/00; C08L101/00; H01L23/12; H05K1/11; H05K3/00; H05K3/42; C08K3/00; C08L101/00; (IPC1-7): C08K3/00; C08L101/00; H05K1/11; H01L23/12; H05K3/00; H05K3/42*

- European:

**Application number:** JP20000377478 20001212

**Priority number(s):** JP20000377478 20001212

**Abstract of JP 2002185097 (A)**

**PROBLEM TO BE SOLVED:** To provide a connecting method exhibiting proper accuracy and efficiency, a circuit board using that method, a semiconductor package, and to provide its manufacturing method. **SOLUTION:** In the method for connecting a conductor buried in an insulating resin with a conductor on the surface of the insulating resin, an opening is made by removing the surface conductor from a part where the interval between the embedded conductor and the surface conductor is 50  $\mu\text{m}$  or less, the insulating resin exposed to the opening is removed, and then the buried conductor is connected with the surface conductor through plating. The buried conductor is used in a circuit board for connecting the surface conductor with an outer layer conductor formed on the insulating resin layer opposite to the surface conductor.; A method for producing the circuit board, a semiconductor package and its manufacturing method, are also provided.

.....  
Data supplied from the *esp@cenet* database — Worldwide